

Product Description

Peregrine's PE3236 is a high performance integer-N PLL capable of frequency synthesis up to 2.2 GHz. The superior phase noise performance of the PE3236 is ideal for applications such as LMDS / MMDS / WLL basestations and demanding terrestrial systems.

The PE3236 features a 10/11 dual modulus prescaler, counters and a phase comparator as shown in Figure 1. Counter values are programmable through either a serial or parallel interface and can also be directly hard wired. This programming flexibility, combined with the dual latch architecture enabling ping-pong loading of the main divide counter, makes these PLLs well suited as the core for fractional-N or sigma-delta implementation.

The PE3236 is optimized for terrestrial applications. It is manufactured on Peregrine's UltraCMOS™ process, a patented variation of silicon-on-insulator (SOI) technology on a sapphire substrate, offering the performance of GaAs with the economy and integration of conventional CMOS.

Features

- 2.2 GHz operation
- $\div 10/11$ dual modulus prescaler
- Internal phase detector
- Serial, parallel or hardwired programmable
- Low power— 22 mA at 3 V
- Q3236 PLL replacement
- Ultra-low phase noise
- Available in 44-lead PLCC package

Figure 1. Block Diagram

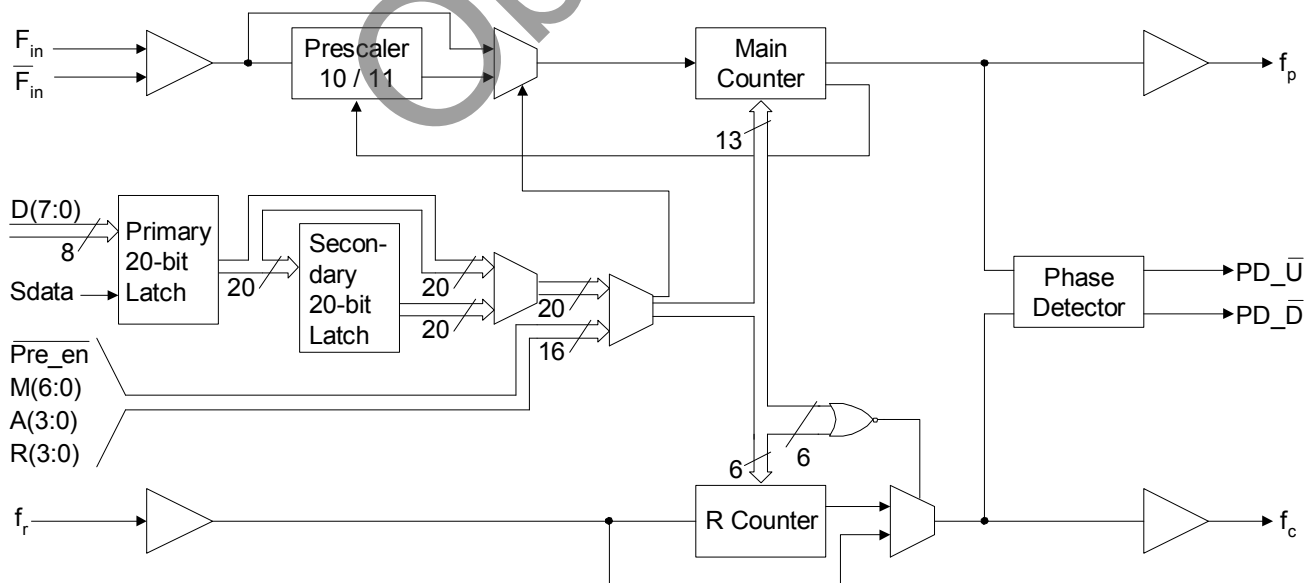
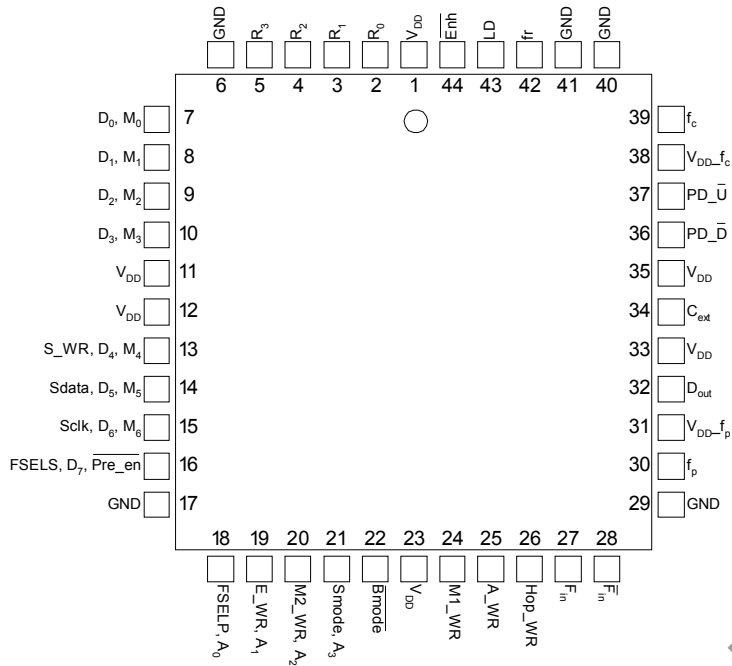
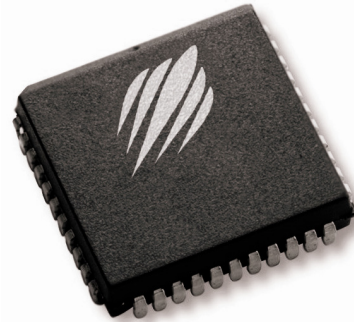


Figure 2. Pin Configurations (Top View)

Figure 3. Package Type
44-lead PLCC

Table 1. Pin Descriptions

| Pin No. | Pin Name | Interface Mode | Type | Description |
|---------|-----------------|----------------|----------|---|
| 1 | V _{DD} | ALL | (Note 1) | Power supply input. Input may range from 2.85 V to 3.15 V. Bypassing recommended. |
| 2 | R ₀ | Direct | Input | R Counter bit0 (LSB). |
| 3 | R ₁ | Direct | Input | R Counter bit1. |
| 4 | R ₂ | Direct | Input | R Counter bit2. |
| 5 | R ₃ | Direct | Input | R Counter bit3. |
| 6 | GND | ALL | (Note 1) | Ground. |
| 7 | D ₀ | Parallel | Input | Parallel data bus bit0 (LSB). |
| | M ₀ | Direct | Input | M Counter bit0 (LSB). |
| 8 | D ₁ | Parallel | Input | Parallel data bus bit1. |
| | M ₁ | Direct | Input | M Counter bit1. |
| 9 | D ₂ | Parallel | Input | Parallel data bus bit2. |
| | M ₂ | Direct | Input | M Counter bit2. |
| 10 | D ₃ | Parallel | Input | Parallel data bus bit3. |
| | M ₃ | Direct | Input | M Counter bit3. |
| 11 | V _{DD} | ALL | (Note 1) | Same as pin 1. |
| 12 | V _{DD} | ALL | (Note 1) | Same as pin 1. |

Table 1. Pin Descriptions (continued)

| Pin No. | Pin Name | Interface Mode | Type | Description |
|---------|-----------------|------------------|----------|---|
| 13 | S_WR | Serial | Input | Serial load enable input. While S_WR is "low", Sdata can be serially clocked. Primary register data are transferred to the secondary register on S_WR or Hop_WR rising edge. |
| | D ₄ | Parallel | Input | Parallel data bus bit4. |
| | M ₄ | Direct | Input | M Counter bit4. |
| 14 | Sdata | Serial | Input | Binary serial data input. Input data entered MSB first. |
| | D ₅ | Parallel | Input | Parallel data bus bit5. |
| | M ₅ | Direct | Input | M Counter bit5. |
| 15 | Sclk | Serial | Input | Serial clock input. Sdata is clocked serially into the 20-bit primary register (E_WR "low") or the 8-bit enhancement register (E_WR "high") on the rising edge of Sclk. |
| | D ₆ | Parallel | Input | Parallel data bus bit6. |
| | M ₆ | Direct | Input | M Counter bit6. |
| 16 | FSELS | Serial | Input | Selects contents of primary register (FSELS=1) or secondary register (FSELS=0) for programming of internal counters while in Serial Interface Mode. |
| | D ₇ | Parallel | Input | Parallel data bus bit7 (MSB). |
| | Pre_en | Direct | Input | Prescaler enable, active "low". When "high", F _{in} bypasses the prescaler. |
| 17 | GND | ALL | | Ground. |
| 18 | FSELP | Parallel | Input | Selects contents of primary register (FSELP=1) or secondary register (FSELP=0) for programming of internal counters while in Parallel Interface Mode. |
| | A ₀ | Direct | Input | A Counter bit0 (LSB). |
| 19 | E_WR | Serial | Input | Enhancement register write enable. While E_WR is "high", Sdata can be serially clocked into the enhancement register on the rising edge of Sclk. |
| | | Parallel | Input | Enhancement register write. D[7:0] are latched into the enhancement register on the rising edge of E_WR. |
| | A ₁ | Direct | Input | A Counter bit1. |
| 20 | M2_WR | Parallel | Input | M2 write. D[3:0] are latched into the primary register (R[5:4], M[8:7]) on the rising edge of M2_WR. |
| | A ₂ | Direct | Input | A Counter bit2. |
| 21 | Smode | Serial, Parallel | Input | Selects serial bus interface mode (Bmode=0, Smode=1) or Parallel Interface Mode (Bmode=0, Smode=0). |
| | A ₃ | Direct | Input | A Counter bit3 (MSB). |
| 22 | Bmode | ALL | Input | Selects direct interface mode (Bmode=1). |
| 23 | V _{DD} | ALL | (Note 1) | Same as pin 1. |
| 24 | M1_WR | Parallel | Input | M1 write. D[7:0] are latched into the primary register (Pre_en, M[6:0]) on the rising edge of M1_WR. |
| 25 | A_WR | Parallel | Input | A write. D[7:0] are latched into the primary register (R[3:0], A[3:0]) on the rising edge of A_WR. |
| 26 | Hop_WR | Serial, Parallel | Input | Hop write. The contents of the primary register are latched into the secondary register on the rising edge of Hop_WR. |
| 27 | F _{in} | ALL | Input | Prescaler input from the VCO. 2.2 GHz max frequency. |
| 28 | F _{in} | ALL | Input | Prescaler complementary input. A bypass capacitor in series with a 51 Ω resistor should be placed as close as possible to this pin and be connected directly to the ground plane. |
| 29 | GND | ALL | | Ground. |

Table 1. Pin Descriptions (continued)

| Pin No. | Pin Name | Interface Mode | Type | Description |
|---------|-------------------------|------------------|---------------|--|
| 30 | f_p | ALL | Output | Monitor pin for main divider output. Switching activity can be disabled through enhancement register programming or by floating or grounding V_{DD} pin 31. |
| 31 | V_{DD-f_p} | ALL | (Note 2) | V_{DD} for f_p . |
| 32 | Dout | Serial, Parallel | Output | Data Out. The MSEL signal and the raw prescaler output are available on Dout through enhancement register programming. |
| 33 | V_{DD} | ALL | (Note 1) | Same as pin 1. |
| 34 | Cext | ALL | Output | Logical "NAND" of PD_U and PD_D terminated through an on chip, 2 k Ω series resistor. Connecting Cext to an external capacitor will low pass filter the input to the inverting amplifier used for driving LD. |
| 35 | V_{DD} | ALL | (Note 1) | Same as pin 1. |
| 36 | PD_D | ALL | Output | PD_D is pulse down when f_p leads f_c . |
| 37 | PD_U | ALL | | PD_U is pulse down when f_c leads f_p . |
| 38 | V_{DD-f_c} | ALL | (Note 2) | V_{DD} for f_c . |
| 39 | f_c | ALL | Output | Monitor pin for reference divider output. Switching activity can be disabled through enhancement register programming or by floating or grounding V_{DD} pin 38. |
| 40 | GND | ALL | | Ground. |
| 41 | GND | ALL | | Ground. |
| 42 | f_r | ALL | Input | Reference frequency input. |
| 43 | LD | ALL | Output, OD | Lock detect and open drain logical inversion of Cext. When the loop is in lock, LD is high impedance, otherwise LD is a logic low ("0"). |
| 44 | $\overline{\text{Enh}}$ | Serial, Parallel | Input | Enhancement mode. When asserted low ("0"), enhancement register bits are functional. |

Note 1: V_{DD} pins 1, 11, 12, 23, 31, 33, 35, and 38 are connected by diodes and must be supplied with the same positive voltage level.

Note 2: V_{DD} pins 31 and 38 are used to power the f_p and f_c outputs and can alternatively be left floating or connected to GND to disable the f_p and f_c outputs.

Table 2. Absolute Maximum Ratings

| Symbol | Parameter/Conditions | Min | Max | Units |
|-----------|---------------------------|------|----------------|-------|
| V_{DD} | Supply voltage | -0.3 | 4.0 | V |
| V_I | Voltage on any input | -0.3 | $V_{DD} + 0.3$ | V |
| I_I | DC into any input | -10 | +10 | mA |
| I_O | DC into any output | -10 | +10 | mA |
| T_{stg} | Storage temperature range | -65 | 150 | °C |

Table 3. Operating Ratings

| Symbol | Parameter/Conditions | Min | Max | Units |
|----------|-------------------------------------|------|------|-------|
| V_{DD} | Supply voltage | 2.85 | 3.15 | V |
| T_A | Operating ambient temperature range | -40 | 85 | °C |

Table 4. ESD Ratings

| Symbol | Parameter/Conditions | Level | Units |
|-----------|--------------------------------|-------|-------|
| V_{ESD} | ESD voltage (Human Body Model) | 1000 | V |

Note 1: Periodically sampled, not 100% tested. Tested per MIL-STD-883, M3015 C2

Electrostatic Discharge (ESD) Precautions

When handling this UltraCMOS™ device, observe the same precautions that you would use with other ESD-sensitive devices. Although this device contains circuitry to protect it from damage due to ESD, precautions should be taken to avoid exceeding the specified rating in Table 4.

Latch-Up Avoidance

Unlike conventional CMOS devices, UltraCMOS™ devices are immune to latch-up.

Table 5. DC Characteristics: $V_{DD} = 3.0\text{ V}$, $-40^\circ\text{ C} < T_A < 85^\circ\text{ C}$, unless otherwise specified

| Symbol | Parameter | Conditions | Min | Typ | Max | Units |
|--|---|---|---------------------|-----|---------------------|-------|
| I_{DD} | Operational supply current; Prescaler enabled | $V_{DD} = 2.85\text{ to }3.15\text{ V}$ | | 22 | 35 | mA |
| Digital Inputs: All except f_r , R_0 , F_{in} , F_{in} | | | | | | |
| V_{IH} | High level input voltage | $V_{DD} = 2.85\text{ to }3.15\text{ V}$ | $0.7 \times V_{DD}$ | | | V |
| V_{IL} | Low level input voltage | $V_{DD} = 2.85\text{ to }3.15\text{ V}$ | | | $0.3 \times V_{DD}$ | V |
| I_{IH} | High level input current | $V_{IH} = V_{DD} = 3.15\text{ V}$ | | | +1 | μA |
| I_{IL} | Low level input current | $V_{IL} = 0, V_{DD} = 3.15\text{ V}$ | -1 | | | μA |
| Reference Divider input: f_r | | | | | | |
| I_{IHR} | High level input current | $V_{IH} = V_{DD} = 3.15\text{ V}$ | | | +100 | μA |
| I_{ILR} | Low level input current | $V_{IL} = 0, V_{DD} = 3.15\text{ V}$ | -100 | | | μA |
| R0 Input (Pull-up Resistor): R_0 | | | | | | |
| I_{IHRO} | High level input current | $V_{IH} = V_{DD} = 3.15\text{ V}$ | | | +5 | μA |
| I_{ILRO} | Low level input current | $V_{IL} = 0, V_{DD} = 3.15\text{ V}$ | -5 | | | μA |
| Counter and phase detector outputs: f_c , f_p | | | | | | |
| V_{OLD} | Output voltage LOW | $I_{out} = 6\text{ mA}$ | | | 0.4 | V |
| V_{OHD} | Output voltage HIGH | $I_{out} = -3\text{ mA}$ | $V_{DD} - 0.4$ | | | V |
| Lock detect outputs: C_{ext} , LD | | | | | | |
| V_{OLC} | Output voltage LOW, C_{ext} | $I_{out} = 0.1\text{ mA}$ | | | 0.4 | V |
| V_{OHC} | Output voltage HIGH, C_{ext} | $I_{out} = -0.1\text{ mA}$ | $V_{DD} - 0.4$ | | | V |
| V_{OLLD} | Output voltage LOW, LD | $I_{out} = 1\text{ mA}$ | | | 0.4 | V |

Table 6. AC Characteristics: $V_{DD} = 3.0\text{ V}$, $-40^\circ\text{ C} < T_A < 85^\circ\text{ C}$, unless otherwise specified

| Symbol | Parameter | Conditions | Min | Max | Units |
|---|--|----------------------|-----|------|--------|
| Control Interface and Latches (see Figures 4, 5, 6) | | | | | |
| f_{CLK} | Serial data clock frequency | (Note 1) | | 10 | MHz |
| t_{CLKH} | Serial clock HIGH time | | 30 | | ns |
| t_{CLKL} | Serial clock LOW time | | 30 | | ns |
| t_{DSU} | Sdata set-up time to Sclk rising edge, D[7:0] set-up time to M1_WR, M2_WR, A_WR rising edge | | 10 | | ns |
| t_{DHLD} | Sdata hold time after Sclk rising edge, D[7:0] hold time to M1_WR, M2_WR, A_WR, E_WR rising edge | | 10 | | ns |
| t_{PW} | S_WR, M1_WR, M2_WR, A_WR, E_WR pulse width | | 30 | | ns |
| t_{CWR} | Sclk rising edge to S_WR rising edge. S_WR, M1_WR, M2_WR, A_WR falling edge to Hop_WR rising edge | | 30 | | ns |
| t_{CE} | Sclk falling edge to E_WR transition | | 30 | | ns |
| t_{WRC} | S_WR falling edge to Sclk rising edge. Hop_WR falling edge to S_WR, M1_WR, M2_WR, A_WR rising edge | | 30 | | ns |
| t_{EC} | E_WR transition to Sclk rising edge | | 30 | | ns |
| Main Divider (Including Prescaler) | | | | | |
| F_{in} | Operating frequency | | 200 | 2200 | MHz |
| P_{Fin} | Input level range | External AC coupling | -5 | 5 | dBm |
| Main Divider (Prescaler Bypassed) | | | | | |
| F_{in} | Operating frequency | | 20 | 220 | MHz |
| P_{Fin} | Input level range | External AC coupling | -5 | 5 | dBm |
| Reference Divider | | | | | |
| f_r | Operating frequency | (Note 3) | | 100 | MHz |
| P_{fr} | Reference input power (Note 2) | Single ended input | -2 | | dBm |
| Phase Detector | | | | | |
| f_c | Comparison frequency | (Note 3) | | 20 | MHz |
| SSB Phase Noise ($F_{in} = 1.3\text{ GHz}$, $f_r = 10\text{ MHz}$, $f_c = 1.25\text{ MHz}$, $LBW = 70\text{ kHz}$, $V_{DD} = 3.0\text{ V}$, $Temp = -40^\circ\text{ C}$) | | | | | |
| | | 100 Hz Offset | | -75 | dBc/Hz |
| | | 1 kHz Offset | | -85 | dBc/Hz |

Note 1: Fclk is verified during the functional pattern test. Serial programming sections of the functional pattern are clocked at 10 MHz to verify Fclk specification.

Note 2: CMOS logic levels can be used to drive the reference input if DC coupled. Voltage input needs to be a minimum of 0.5 Vp-p. For optimum phase noise performance, the reference input falling edge rate should be faster than 80mV/ns.

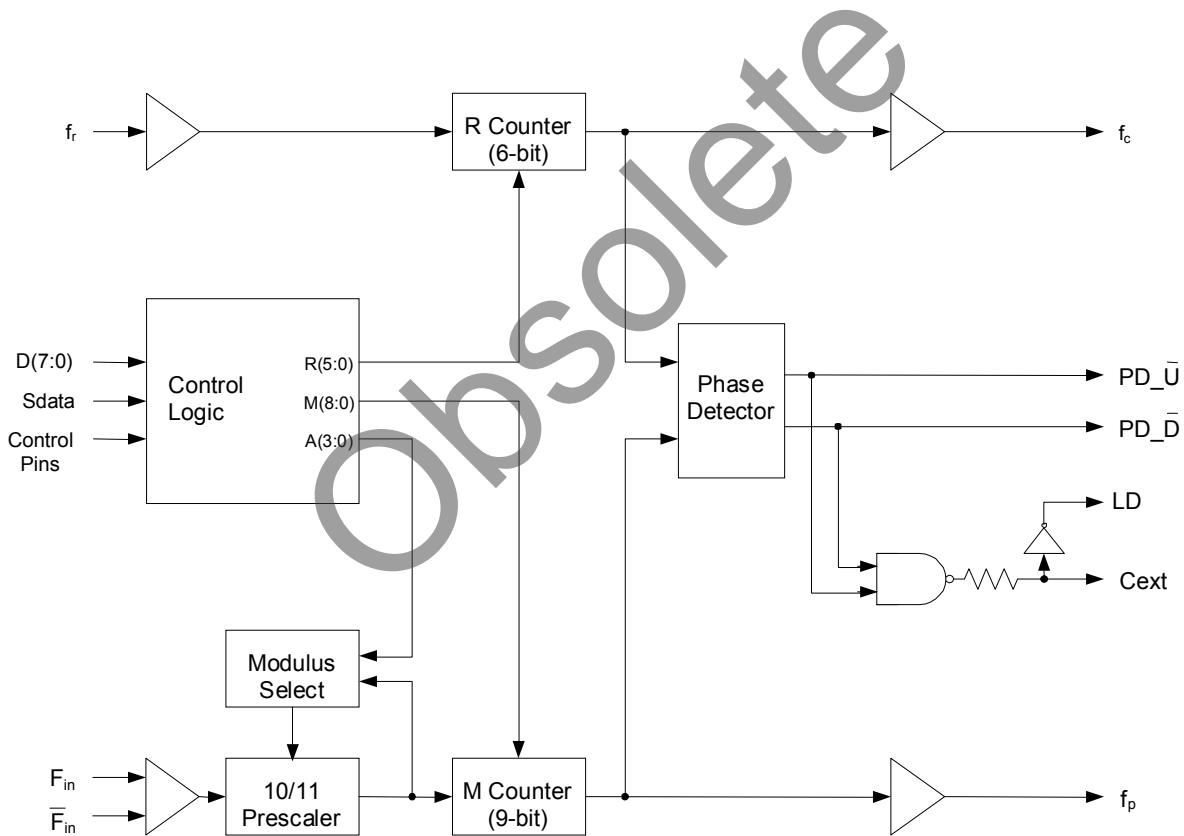
Note 3: Parameter is guaranteed through characterization only and is not tested.

Functional Description

The PE3236 consists of a prescaler, counters, a phase detector and control logic. The dual modulus prescaler divides the VCO frequency by either 10 or 11, depending on the value of the modulus select. Counters “R” and “M” divide the reference and prescaler output, respectively, by integer values stored in a 20-bit register. An additional counter (“A”) is used in the modulus select logic. The phase-frequency detector

generates up and down frequency control signals. The control logic includes a selectable chip interface. Data can be written via serial bus, parallel bus, or hardwired direct to the pins. There are also various operational and test modes and lock detect.

Figure 4. Functional Block Diagram



Main Counter Chain

The main counter chain divides the RF input frequency, F_{in} , by an integer derived from the user defined values in the “M” and “A” counters. It is composed of the 10/11 dual modulus prescaler, modulus select logic, and 9 bit M counter. Setting $\overline{Pre_en}$ “low” enables the 10/11 prescaler. Setting $\overline{Pre_en}$ “high” allows F_{in} to bypass the prescaler and powers down the prescaler.

The output from the main counter chain, f_p , is related to the VCO frequency, F_{in} , by the following equation:

$$f_p = F_{in} / [10 \times (M + 1) + A] \quad (1)$$

where $A \leq M + 1$, $1 \leq M \leq 511$

When the loop is locked, F_{in} is related to the reference frequency, f_r , by the following equation:

$$F_{in} = [10 \times (M + 1) + A] \times (f_r / (R+1)) \quad (2)$$

where $A \leq M + 1$, $1 \leq M \leq 511$

A consequence of the upper limit on A is that F_{in} must be greater than or equal to $90 \times (f_r / (R+1))$ to obtain contiguous channels. Programming the M Counter with the minimum value of “1” will result in a minimum M Counter divide ratio of “2”.

When the prescaler is bypassed, the equation becomes:

$$F_{in} = (M + 1) \times (f_r / (R+1)) \quad (3)$$

where $1 \leq M \leq 511$

In Direct Interface Mode, main counter inputs M_7 and M_8 are internally forced low.

Reference Counter

The reference counter chain divides the reference frequency, f_r , down to the phase detector comparison frequency, f_c .

The output frequency of the 6-bit R Counter is related to the reference frequency by the following equation:

$$f_c = f_r / (R + 1) \quad (4)$$

where $0 \leq R \leq 63$

Note that programming R equal to “0” will pass the reference frequency, f_r , directly to the phase detector.

In Direct Interface Mode, R Counter inputs R_4 and R_5 are internally forced low (“0”).

Register Programming

Parallel Interface Mode

Parallel Interface Mode is selected by setting the \overline{Bmode} input “low” and the \overline{Smode} input “low”.

Parallel input data, $D[7:0]$, are latched in a parallel fashion into one of three, 8-bit primary register sections on the rising edge of $M1_WR$, $M2_WR$, or A_WR per the mapping shown in Table 7 on page 9. The contents of the primary register are transferred into a secondary register on the rising edge of Hop_WR according to the timing diagram shown in Figure 5. Data are transferred to the counters as shown in Table 7 on page 9.

The secondary register acts as a buffer to allow rapid changes to the VCO frequency. This double buffering for “ping-pong” counter control is programmed via the \overline{FSELP} input. When \overline{FSELP} is “high”, the primary register contents set the counter inputs. When \overline{FSELP} is “low”, the secondary register contents are utilized.

Parallel input data, $D[7:0]$, are latched into the enhancement register on the rising edge of E_WR according to the timing diagram shown in Figure 5. This data provides control bits as shown in Table 8 on page 9 with bit functionality enabled by asserting the \overline{Enh} input “low”.

Serial Interface Mode

Serial Interface Mode is selected by setting the \overline{Bmode} input “low” and the \overline{Smode} input “high”.

While the $\overline{E_WR}$ input is “low” and the $\overline{S_WR}$ input is “low”, serial input data (\overline{Sdata} input), B_0 to B_{19} , are clocked serially into the primary register on the rising edge of \overline{Sclk} , MSB (B_0) first. The contents from the primary register are transferred into the secondary register on the rising edge of either $\overline{S_WR}$ or $\overline{Hop_WR}$ according to the timing diagram shown in Figures 5-6. Data are transferred to the counters as shown in Table 7 on page 9.

The double buffering provided by the primary and secondary registers allows for “ping-pong” counter control using the \overline{FSELS} input. When \overline{FSELS} is “high”, the primary register contents set the counter inputs. When \overline{FSELS} is “low”, the secondary register contents are utilized.

While the $\overline{E_WR}$ input is “high” and the $\overline{S_WR}$ input is “low”, serial input data (\overline{Sdata} input), B_0

to B₇, are clocked serially into the enhancement register on the rising edge of Sclk, MSB (B₀) first. The enhancement register is double buffered to prevent inadvertent control changes during serial loading, with buffer capture of the serially entered data performed on the falling edge of E_WR according to the timing diagram shown in Figure 6. After the falling edge of E_WR, the data provide control bits as shown in Table 8 on with bit functionality enabled by asserting the Enh input “low”.

Direct Interface Mode

Direct Interface Mode is selected by setting the Bmode input “high”.

Counter control bits are set directly at the pins as shown in Table 7. In Direct Interface Mode, main counter inputs M₇ and M₈, and R Counter inputs R₄ and R₅ are internally forced low (“0”).

Table 7. Primary Register Programming

| Interface Mode | Enh | Bmode | Smode | R ₅ | R ₄ | M ₈ | M ₇ | Pre_en | M ₆ | M ₅ | M ₄ | M ₃ | M ₂ | M ₁ | M ₀ | R ₃ | R ₂ | R ₁ | R ₀ | A ₃ | A ₂ | A ₁ | A ₀ |
|----------------|-----|-------|-------|------------------------|----------------|----------------|----------------|------------------------|----------------|----------------|----------------|----------------|----------------|-----------------|-----------------|-----------------------|-----------------|-----------------|-----------------|-----------------|-----------------|-----------------|-----------------|
| Parallel | 1 | 0 | 0 | M2_WR rising edge load | | | | M1_WR rising edge load | | | | | | | | A_WR rising edge load | | | | | | | |
| | | | | D ₃ | D ₂ | D ₁ | D ₀ | D ₇ | D ₆ | D ₅ | D ₄ | D ₃ | D ₂ | D ₁ | D ₀ | D ₇ | D ₆ | D ₅ | D ₄ | D ₃ | D ₂ | D ₁ | D ₀ |
| Serial* | 1 | 0 | 1 | B ₀ | B ₁ | B ₂ | B ₃ | B ₄ | B ₅ | B ₆ | B ₇ | B ₈ | B ₉ | B ₁₀ | B ₁₁ | B ₁₂ | B ₁₃ | B ₁₄ | B ₁₅ | B ₁₆ | B ₁₇ | B ₁₈ | B ₁₉ |
| Direct | 1 | 1 | X | 0 | 0 | 0 | 0 | Pre_en | M ₆ | M ₅ | M ₄ | M ₃ | M ₂ | M ₁ | M ₀ | R ₃ | R ₂ | R ₁ | R ₀ | A ₃ | A ₂ | A ₁ | A ₀ |

*Serial data clocked serially on Sclk rising edge while E_WR “low” and captured in secondary register on S_WR rising edge.



Table 8. Enhancement Register Programming

| Interface Mode | Enh | Bmode | Smode | Reserved | Reserved | Reserved | Power down | Counter load | MSEL output | Prescaler output | f _c , f _p OE |
|----------------|-----|-------|-------|-----------------------|----------------|----------------|----------------|----------------|----------------|------------------|------------------------------------|
| Parallel | 0 | X | 0 | E_WR rising edge load | | | | | | | |
| | | | | D ₇ | D ₆ | D ₅ | D ₄ | D ₃ | D ₂ | D ₁ | D ₀ |
| Serial* | 0 | X | 1 | B ₀ | B ₁ | B ₂ | B ₃ | B ₄ | B ₅ | B ₆ | B ₇ |

*Serial data clocked serially on Sclk rising edge while E_WR “high” and captured in the double buffer on E_WR falling edge.



Figure 5. Parallel Interface Mode Timing Diagram

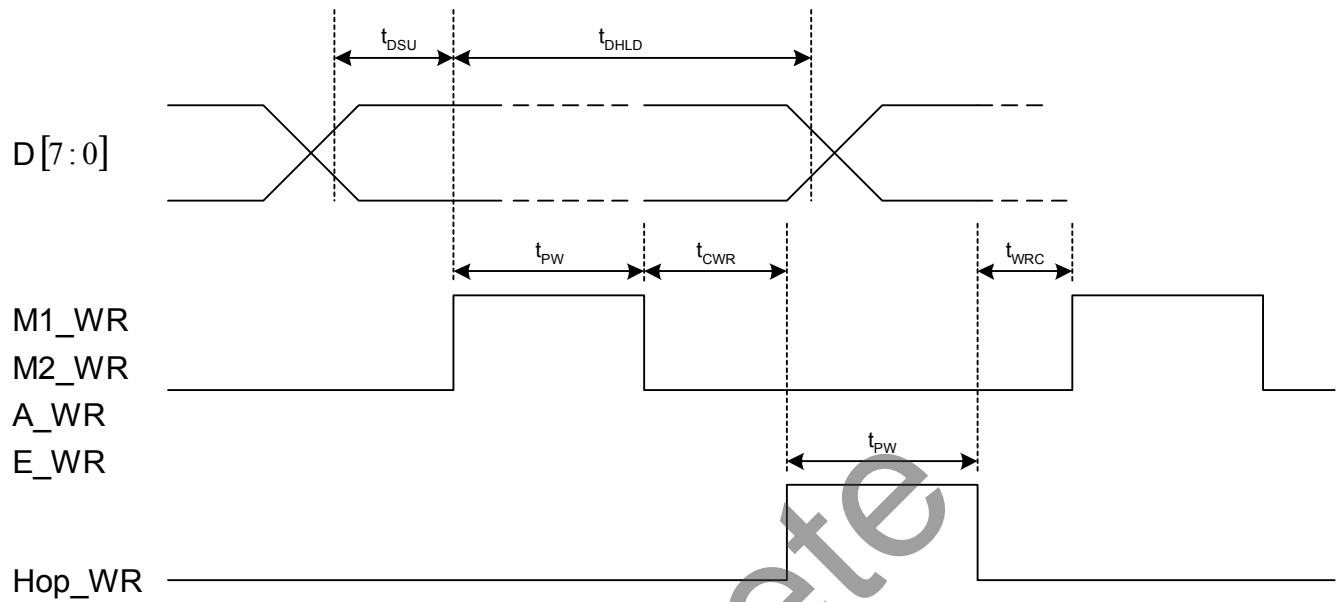
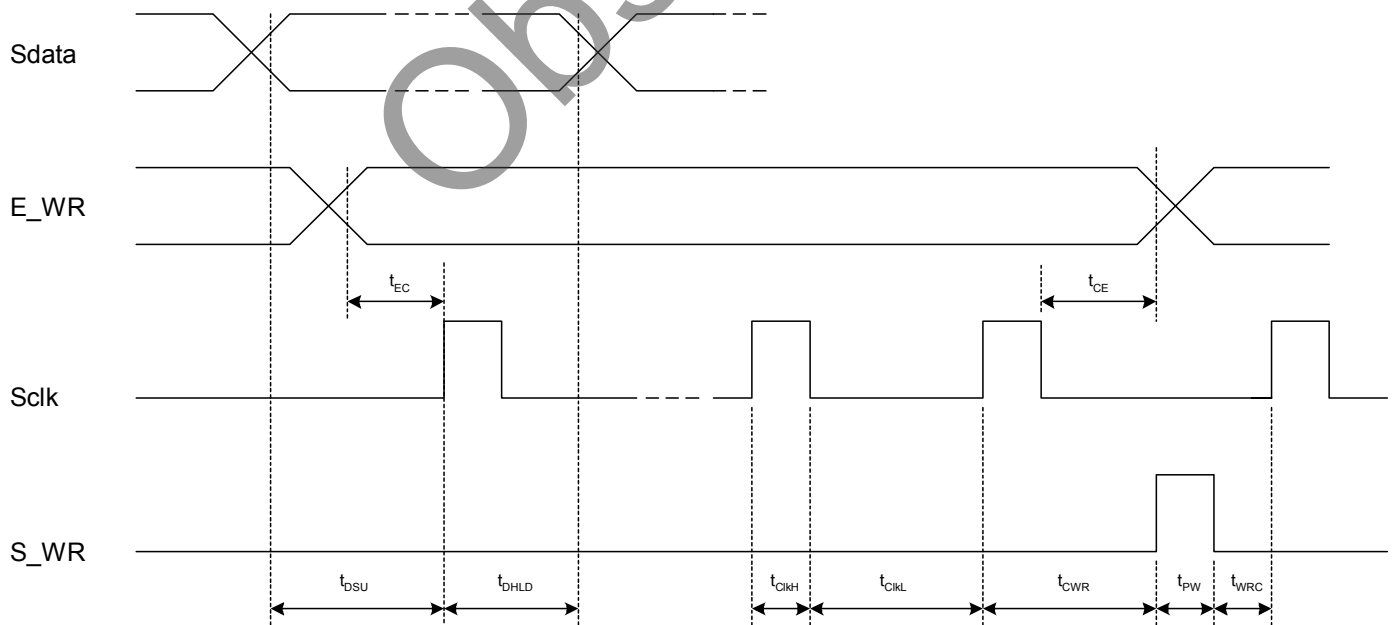


Figure 6. Serial Interface Mode Timing Diagram



Enhancement Register

The functions of the enhancement register bits are shown below with all bits active “high”.

Table 9. Enhancement Register Bit Functionality

| Bit Function | | Description |
|--------------|------------------|---|
| Bit 0 | Reserved** | |
| Bit 1 | Reserved** | |
| Bit 2 | Reserved** | |
| Bit 3 | Power down | Power down of all functions except programming interface. |
| Bit 4 | Counter load | Immediate and continuous load of counter programming as directed by the \overline{Bmode} and \overline{Smode} inputs. |
| Bit 5 | MSEL output | Drives the internal dual modulus prescaler modulus select (MSEL) onto the Dout output. |
| Bit 6 | Prescaler output | Drives the raw internal prescaler output onto the Dout output. |
| Bit 7 | f_p, f_c OE | f_p, f_c outputs disabled. |

** Program to 0

Phase Detector

The phase detector is triggered by rising edges from the main Counter (f_p) and the reference counter (f_c). It has two outputs, namely PD_U, and PD_D. If the divided VCO leads the divided reference in phase or frequency (f_p leads f_c), PD_D pulses “low”. If the divided reference leads the divided VCO in phase or frequency (f_c leads f_p), PD_U pulses “low”. The width of either pulse is directly proportional to phase offset between the two input signals, f_p and f_c .

PD_U and PD_D drive an active loop filter which controls the VCO tune voltage. PD_U pulses result in an increase in VCO frequency and PD_D results in a decrease in VCO frequency.

A lock detect output, LD is also provided, via the pin Cext. Cext is the logical “NAND” of PD_U and PD_D waveforms, which is driven through a series 2 k Ω resistor. Connecting Cext to an external shunt capacitor provides integration. Cext also drives the input of an internal inverting comparator with an open drain output. Thus LD is an “AND” function of PD_U and PD_D.

Figure 7. PE3236 Typical Phase Noise vs. Offset (V_{DD} = 3.0 V, Temp = 25 °C)

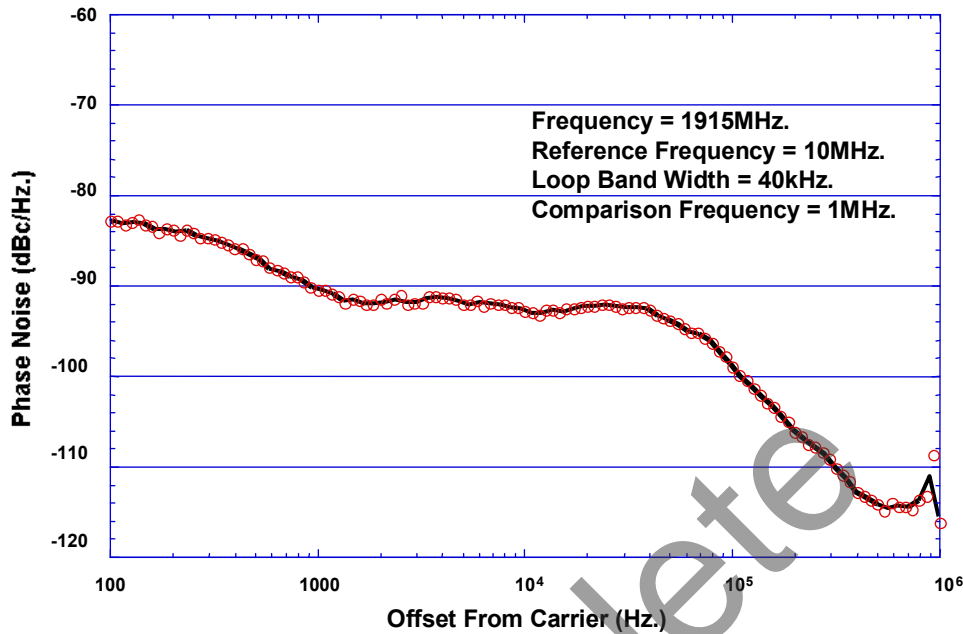
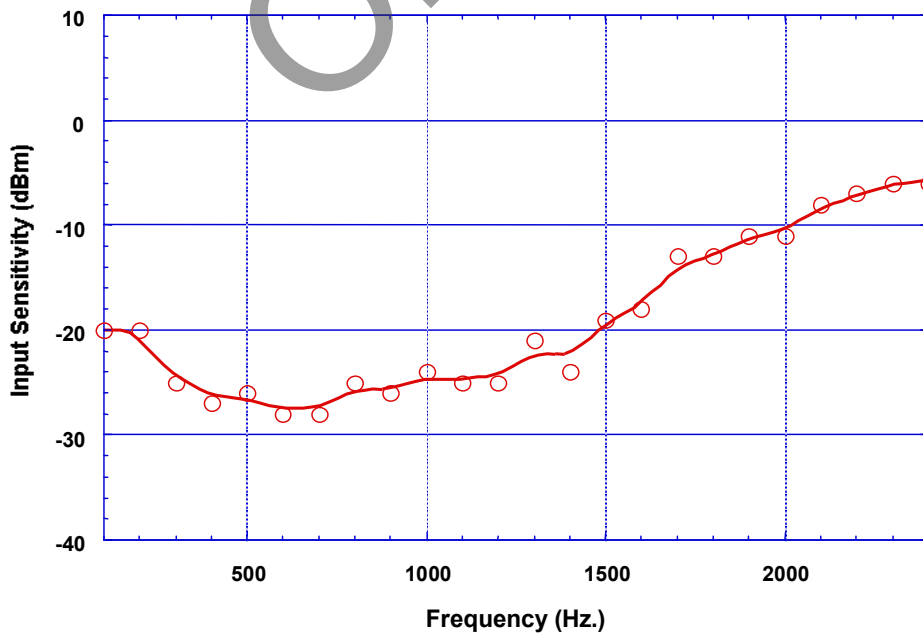


Figure 8. PE3236 Typical Input Sensitivity vs. Frequency (V_{DD} = 3.0 V, Temp = 25 °C)



Handling Requirements

All surface mount products which do not meet Level 1 moisture sensitivity requirements are processed through dry bake and pack procedure. The necessary data is recorded on the caution label of each shipment. The 44-lead PLCC package is moisture sensitivity Level 3.

Level 3 Caution Label

The caution label should contain the following information for Level 3 devices:

1. Calculated shelf life in sealed bag: 12 months at $<40\text{ }^{\circ}\text{C}$ and $<90\%$ relative humidity (RH)
2. Peak package body temperature is $225\text{ }^{\circ}\text{C}$.
3. After bag is opened, devices that will be subjected to reflow solder or other high temperature process must
 - a) Be mounted within 168 hours of factory conditions $<30\text{ }^{\circ}\text{C}/60\%$ RH, **or**
 - b) Be stored at $<10\%$ RH
4. Devices require bake, before mounting, if:
 - a) Humidity Indicator Card is $> 10\%$ when read at $23 \pm 5\text{ }^{\circ}\text{C}$
 - b) 3a or 3b are not met
5. If baking is required, devices may be baked for 48 hours at $125 +5/-0\text{ }^{\circ}\text{C}$

Note: If device containers cannot be subjected to high temperature or shorter bake times are desired, reference IPC/JEDEC-J-STD-033 for bake procedure.

Level and Body temperature defined by:
IPC/JEDEC-J-STD-020

For Dry Bake Procedures, see:
IPC/JEDEC-J-STD-033

Operator must observe ESD precautions per ESD Control Procedure and Parts Handling and shipping Procedure.

Figure 9. Package Drawing

44-lead PLCC

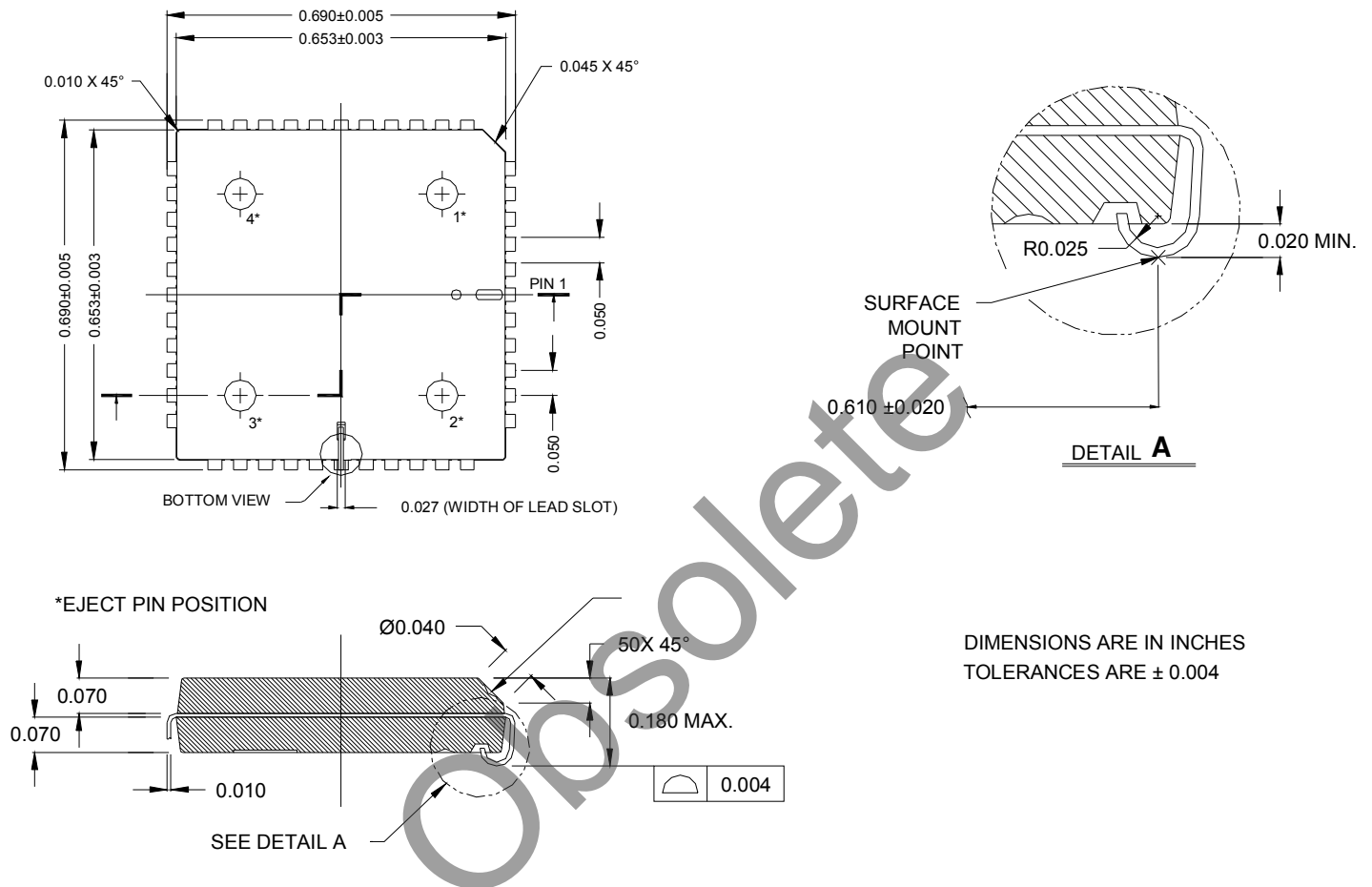


Table 10. Ordering Information

| Order Code | Part Marking | Description | Package | Shipping Method |
|------------|--------------|------------------------|--------------------|-----------------|
| 3236-21 | PE3236 | PE3236-44PLCC-27A | 44-lead PLCC | 27 units / Tube |
| 3236-22 | PE3236 | PE3236-44PLCC-500C | 44-lead PLCC | 500 units / T&R |
| 3236-54 | PE3236 | PE3236G-44PLCC-500C | Green 44-lead PLCC | 500 units / T&R |
| 3236-00 | PE3236EK | PE3236-44PLCC-EVAL KIT | 44-lead PLCC | 1 / Box |

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Web site at: www.psemi.com

Data Sheet Identification

Advance Information

The product is in a formative or design stage. The data sheet contains design target specifications for product development. Specifications and features may change in any manner without notice.

Preliminary Specification

The data sheet contains preliminary data. Additional data may be added at a later date. Peregrine reserves the right to change specifications at any time without notice in order to supply the best possible product.

Product Specification

The data sheet contains final data. In the event Peregrine decides to change the specifications, Peregrine will notify customers of the intended changes by issuing a CNF (Customer Notification Form).

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